ABSTRACT

An improved PCB bond pad (22, 40, 50, 60) having a dimensioned geometry that improves solder re-flow and facilitates outgassing of bubbles generated in solder during re-flow to reduce voiding. The improved PCB bond pad design is particularly useful to improve re-flow for RF devices that are sensitive to voiding in solder after re-flow and provides an excellent ground plane/heat sink connection. The present invention includes a printed circuit board (PCB) having a patterned bond pad defining solder channels (30, 42, 52, and 62). During re-flow, bubbles outgas through the channels from under a contact pad (34) of an overlying IC device thereby providing nearly 100 percent solder coverage at interface of device exposed pad and PCB bond pad.